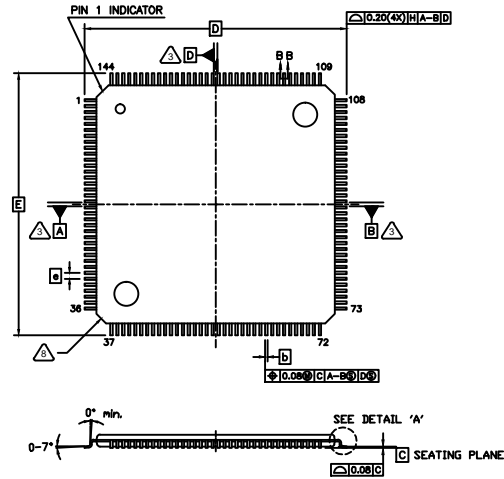
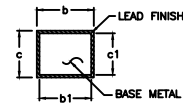
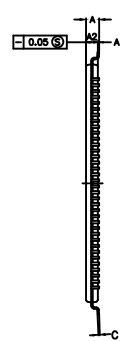




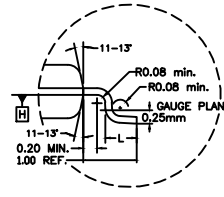
TOP VIEW



SIDE VIEW

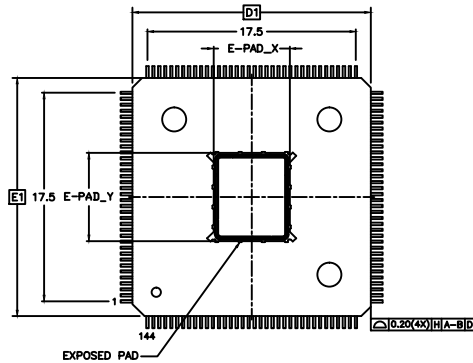


SECTION B-B (15:1)



DETAIL "A"

	SYMBOL	Common Dimensions		
		MIN.	NOM.	MAX.
Total Thickness:	A	1.00	1.10	1.20
Stand Off:	A1	0.05	0.10	0.15
Mold Thickness:	A2	0.95	1.00	1.05
Outer Lead Distance:	D	22.00	BSC.	
Package Size:	D1	20.00	BSC.	
Outer Lead Distance:	E	22.00	BSC.	
Package Size:	E1	20.00	BSC.	
Pin PCB Mounting Length:	L	0.45	0.60	0.75
Lead count:	N	144		
Lead pitch:	e	0.50	BSC.	
L/F Thickness w/plating:	c	0.09	0.127	0.20
L/F Thickness w/o plating:	c1	0.09	—	0.16
Lead width w/plating:	b	0.17	0.22	0.27
Lead width w/o plating:	b1	0.17	0.20	0.23
E-PAD_X:		6.400		
E-PAD_Y:		7.400		



BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. JEDEC REFERENCE: MS-026

Title: Package Outline Drawing	Pkg Type: LQFP/TQFP	Document No: POD-250083	
Product Family: LFMXO4	Pin Count: 144		
Product Name: LFMXO4-010/015/025/050-TSG144	Pkg Size: 20x20 mm	Rev: A	
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